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PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Woo Chul JEON	06/08/2010
Ki Yeol PARK	06/08/2010
Young Hwan PARK	06/08/2010
Jung Hee LEE	06/08/2010

RECEIVING PARTY DATA

Name:	SAMSUNG ELECTRO-MECHANICS CO., LTD.	
Street Address:	314 Maetan 3-Dong, Yeongtong-Gu	
City:	Suwon, Gyunggi-do	
State/Country:	REPUBLIC OF KOREA	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12965640

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	082658-0053	
NAME OF SUBMITTER:	Soyeon (Karen) Pak Laub, Reg. # 39,266	

Total Attachments: 2

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PATENT REEL: 025493 FRAME: 0115 source=082658-0053_Assignment#page2.tif

PATENT REEL: 025493 FRAME: 0116 Attorney Docket No.: 082658-0053

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,					
(1) JEON, Woo Chul (5)					
(2) PARK, Ki Yeol (6)					
(3) PARK, Young Hwan (7)					
(4) LEE, Jung Hee (8)					
who have made a certain new and useful invention, hereby sell, assign and transfer unto					
SAMSUNG ELECTRO-MECHANICS CO., LTD.					
314 Maetan 3-dong, Yeongtong-gu, Suwon, Gyunggi-do, Republic of Korea					
its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING THE SAME					
(a) for which an application for United States Letters Patent was filed on, and identified by United States Application No; or					
(b) for which an application for United States Letters Patent was executed on herewith,					
and the undersigned hereby authorize and request the United States Commissioner for Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;					
AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.					

PATENT REEL: 025493 FRAME: 0117 SIGNED on the dates indicated aside our signatures:

Name: LEE, Jung Hee

	INVENTORS	DATE SIGNED
l)		08/06/2%
	Name: JEON, Woo Chul	,
2)	1/2 /	08/06/20/0
	Name: PARK, Ki Yeol	
3)	JEH	08/06/2010
	Name: PARK, Young Hwan	
4)	Les Tuyles	08/06/2010

PATENT REEL: 025493 FRAME: 0118

RECORDED: 12/14/2010